

ABSTRACT OF THE DISCLOSURE

Outstanding YAG laser marking characteristics can be obtained without electric defects such as a short circuit and leak current and without deforming gold wires by using an epoxy resin composition for semiconductor sealing encapsulating comprising an epoxy resin, a phenol resin, an inorganic filler, a curing accelerator, and a carbon precursor having a specific electric resistivity in a semiconductor region of  $1 \times 10^2 \Omega \cdot \text{cm}$  or more but less than  $1 \times 10^7 \Omega \cdot \text{cm}$  as essential components, wherein the amounts of the inorganic filler and the carbon precursor in the epoxy resin composition are respectively 65-92 wt% and 0.1-5.0 wt%.